射頻濺鍍系統

RF Sputter System

Model：YUTAY (于太)

一、測試目的：

1.沉積金屬薄膜層

二、樣品準備須知及注意事項：

1.金屬靶材須為直徑之3吋靶

2.啟動Diffusion Pump時，須確定油沸後，方可開啟MV閥。

三、限制：

1.機台參數壓力、閥件、流量及功率不可任意調整，違者取消使用資格。

2.提升瓦數時，在100瓦以下須以每半分升20瓦，100瓦以上每分升20瓦為原則。

四、使用方法：

1.系內使用以登記申請，請E2-503研究室的操作員指導操作，數據自行分析為原則。

2.系外單位使用，須經登記申請，並經系主任及負責老師同意後，方可使用。

五、負責老師：王孟菊

RF Sputter System
Model：YUTAY (于太)

I. Purpose:

1. Deposit metallic thin film

II. Sample preparation instructions and precautions:

1. The metal target should be 3 inches in diameter.
2. After starting diffusion pump, it is necessary to make sure oil in diffusion pump is boiling, and then the MV valve can be opened.

III. Restrictions:

1. Not to adjust valves, power, flow rate recklessly
2. While rising power, you should follow:

   Under 100 W, rise 20 W per 30 seconds

   Over 100 W, rise 20 W per minute

IV. Application:

1. Registration for application in advance is required. Users are required to operate the instrument by requesting the students from Lab E2-503.
2. For users outside the department, application should be signed by the chairman of the Chemical Engineering Department and the professor-in-charge for the sputter.

V. Professor-In-Charge: Meng-Jiy Wang (王孟菊)